Sheet 1 of 1

INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

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PATENT & TRADEMARK OFFICE

ATTY. DOCKET NO.	SERIAL NO.
829-590	09/993,897
APPLICANT	
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FILING DATE	**GROUP**
November 27, 2001	2812

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

		DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES	TRANSLATION NO
AR		0 809 288	11/1997	EP			X	

OTHER DOCUMENTS (including Author, Title, Date, Pertinent pages, etc.)

AR		European Search Report dated March 11, 2004
AR		"Sacrificial Wafer Bonding for Planarization After Very Deep Etching", Spiering et al., Journal of Microelectromechanical Systems, September 1995, No. 3, pgs. 151-157 XP000531458
AR		Abstract 01128164.9 (1pg)

*Examiner		Date Considered	07/08/04

Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to application.

Form PTO-FB-A820 (Also PTO-1449)

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